

AMENDMENTS TO THE SPECIFICATION:

Page 1, amend paragraph [0004] as:

[0004] The dedicated testing chooses points to be tested according to circuit layout of a tested printed circuit board and chooses proper spring probes according to the size of the points to be tested and the distance between adjacent points to be tested. Two principles are employed in choosing the spring probes: (1) whether or not, the spring probes include features suitable to test the points; (2) after the receptacles of the probes inserted in the fixing board of test fixture, no short circuit happened. The diameters ~~diameter~~ of receptacles for the spring probes are within the range between 0.45mm to 1.65mm.

Page 2, amend paragraph [0006] as:

[0006] When using the dedicated tester, the test fixture has to be fixed to the press of the tester and the connectors on the test fixture are connected to the tester with flat cables so that each probe is connected to a test node in the tester. When the press is lowered, the spring in the probe is applied by a force so that the plunger of the probe and the point to be tested on the printed circuit board ~~[[is]]~~ are electrically connected ~~[[such]]~~ so that the points to be tested on the printed circuit board become conductive with the test node in the tester because of close contact. This can be used to test the open/short of each trace of the layout.

Page 2, amend paragraph [0008] as:

[0008] The present invention relates to a method for testing a printed circuit board and the method is carried out by using an innovative dedicated test fixture, which

employs conductive rubber and a dedicated ~~specialy shaped~~ printed circuit board. The test fixture can be easily manufactured and is less expensive. The innovative method of the present invention allows for easy test of sophisticated printed circuit boards with small pads arranged in for example 0.1 millimeter width and 0.15 ~~millimeter~~ millimeter gap.

Page 3, amend paragraph [0016] as:

[0016] The present invention relates to a method for testing printed circuit boards. The method is carried out by using a dedicated test fixture that is made of conductive rubber and a dedicated ~~special shaped~~ printed circuit board.

Page 4, amend paragraph [0017] as:

[0017] Referring to Figure 1, step 101 first ~~proceeds, which~~ uses software to choose points to be tested on the printed circuit board. Step 102 then ~~proceeds, which~~ uses all information about the points to be tested and manufactures ~~manufacture~~ a testing board having protrusive metal points. The coordinates of the protrusive metal points on the testing board and the points to be tested on the printed circuit board are the same. There are holes for connectors defined in a side of the testing board of fixture for inserting such ~~that~~ the connectors ~~are inserted~~ to the testing board of fixture.

Page 4, amend paragraph [0018] as:

[0018] Step 103 connects all the protrusive metal points to the holes in a side on the testing board having protrusive metal points by layouts. Step 104 proceeds ~~is preceded~~ and the testing board having protrusive metal points is connected to the dedicated tester

through flat cables so that each protrusive metal point is connected to a test node in the tester.

Page 4, amend paragraph [0019] as:

[0019] ~~After that, In~~ step 105 ~~the is preceded and~~ liquid conductive rubber is coated to the tip of each protrusive metal point. After the liquid conductive rubber is solidified, a knife is used to trim them to make all the conductive rubbers ~~are in~~ flush with each other. Step 106 aligns ~~is then preceded to align~~ the points to be tested on the printed circuit board with the protrusive metal points on the testing board. Then step 107 proceeds ~~is preceded~~ to connect the protrusive metal points with the points to be tested on the printed circuit board by using the pressure from the press and the flexibility of the conductive rubber.

Page 4, amend paragraph [0020] as:

[0020] Because the conductive rubber is flexible, ~~so that~~ it compensates for the differences of height between the points to be tested on the printed circuit board and allows the testing board having protrusive metal points to contact the points to be tested on the printed circuit board in good condition. The result for testing open/short of each trace of layout on the printed circuit board is excellent. If the protrusive metal points are higher than the connection circuits on the testing board, the contact between the protrusive metal points and the points to be tested on the printed circuit board will be much better.

Pages 4-5, amend paragraph [0021] as:

[0021] Figure 2 is a flow chart of a second embodiment of the present invention. In

Figure 2, step 101 first ~~proceeds, which~~ uses software to choose points to be tested on the printed ~~print~~ circuit board. Step 102 then ~~proceeds, which~~ uses all information about the points to be tested and manufactures ~~manufacture~~ a testing board having protrusive metal points. The coordinates of the protrusive metal points on testing board and the points to be tested on the printed ~~print~~ circuit board are the same. The protrusive metal points are higher than the rest of the layout. There are holes for connectors defined in a side of the testing board for inserting ~~such that the connectors are inserted~~ to the testing board.

Page 5, amend paragraph [0022] as:

[0022] Step 103 ~~is preceded, which~~ connects all the protruding metal points to the holes in a side of the testing board having protrusive metal points by layouts. Step 104 proceeds ~~is preceded~~ and the testing board having protrusive metal points is connected to the dedicated tester through flat cables so that each protrusive metal point is connected to a test node in the tester. The protrusive metal points are higher than the rest of the layout.

Page 5, amend paragraph [0023] as:

[0023] Then step 205 proceeds to insert ~~is preceded, inserted~~ a pressure sensitive conductive rubber layer between the testing board having protrusive metal points and the printed circuit board to be tested. Step 206 proceeds ~~is preceded~~ and the press of the tester applies a pressure to the protrusive metal points and the points to be tested on the printed circuit board so that the pressure sensitive conductive rubber senses the pressure layer, which electrically connects the protrusive metal points and the points on the printed circuit board. The open/short of each trace on the printed circuit board can be tested.

Page 5, amend paragraph [0024] as:

[0024] Figure 3 is a flow chart of a third embodiment of the present invention. In Figure 3, step 101 first ~~proceeds, which~~ uses software to choose points to be tested on the printed circuit board. Step 102 then ~~proceeds, which~~ uses all information about the points to be tested and manufactures ~~manufacture~~ a testing board having protrusive metal points. The coordinates of the metal points and the points to be tested on the printed circuit board are the same. There are holes for connectors defined in a side of the testing board for inserting ~~such that~~ the connectors ~~are inserted~~ to the testing board. The number of the holes has to be larger than or equal to the sum of the protrusive metal points.

Page 5, amend paragraph [0025] as:

[0025] Step 103 connects all the protrusive metal points to the holes in a side of the testing board having protrusive metal points by layouts. Step 104 proceeds and the testing board having protrusive metal points is connected to the dedicated tester through flat cables so that each protrusive metal point is connected to a test node in the tester. The protrusive metal points are higher than the rest of the layout.

Page 5, amend paragraph [0026] as:

[0026] Finally, step 305 proceeds, and each protrusive metal point is taped with an electrically z-axis conductive adhesive film which is conductive in vertical direction. Step 306 then proceeds to align all the points to be tested on the printed ~~print~~ circuit board and the protrusive metal points on the testing board. Step 307 employs the pressure of the press of the tester and the flexibility of the conductive adhesive film